

# 2SJ350

## Silicon P Channel MOS FET

REJ03G0859-0200

(Previous: ADE-208-138)

Rev.2.00 Sep 07, 2005

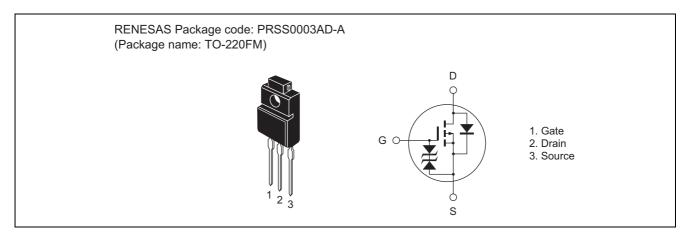
## **Description**

High speed power switching

#### **Features**

- Low on-resistance
- High speed switching
- Low drive current
- 4 V gate drive device can be driven from 5 V source
- Suitable for switching regulator, DC-DC converter

#### **Outline**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Drain to source voltage	$V_{DSS}$	-120	V
Gate to source voltage	$V_{GSS}$	±20	V
Drain current	I <sub>D</sub>	-6	A
Drain peak current	I <sub>D (pulse)</sub> Note 1	-12	Α
Body to drain diode reverse drain current	$I_{DR}$	-6	А
Channel dissipation	Pch Note 2	20	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	−55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1%

2. Value at  $Tc = 25^{\circ}C$ 

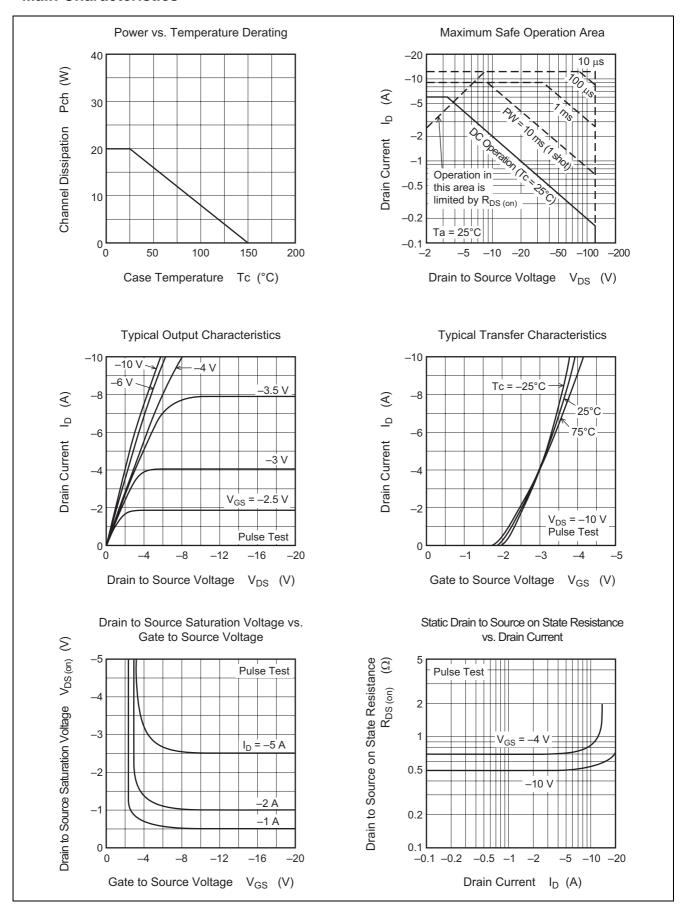
### **Electrical Characteristics**

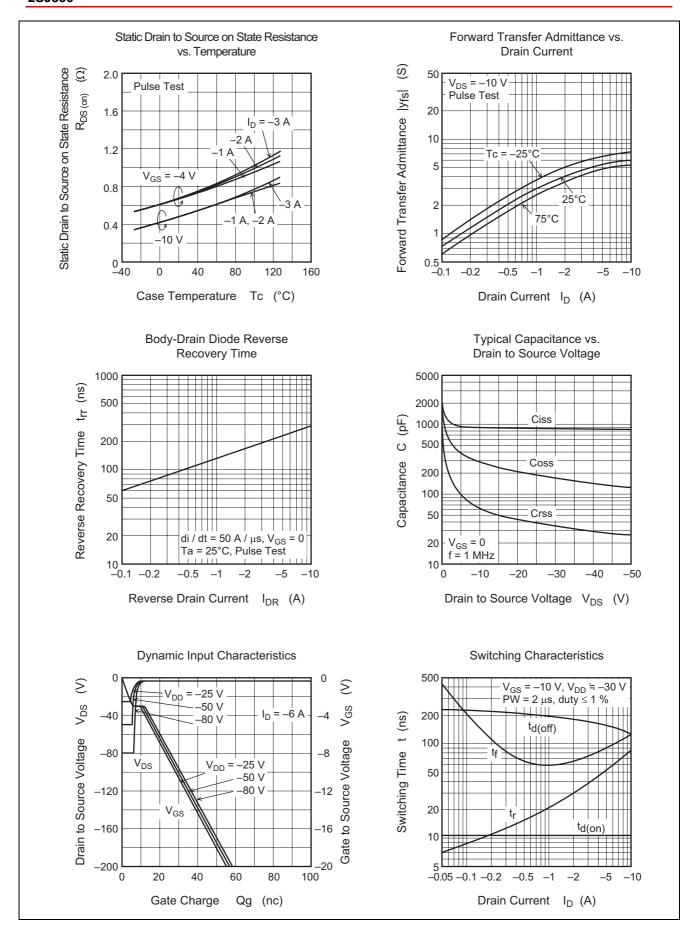
 $(Ta = 25^{\circ}C)$ 

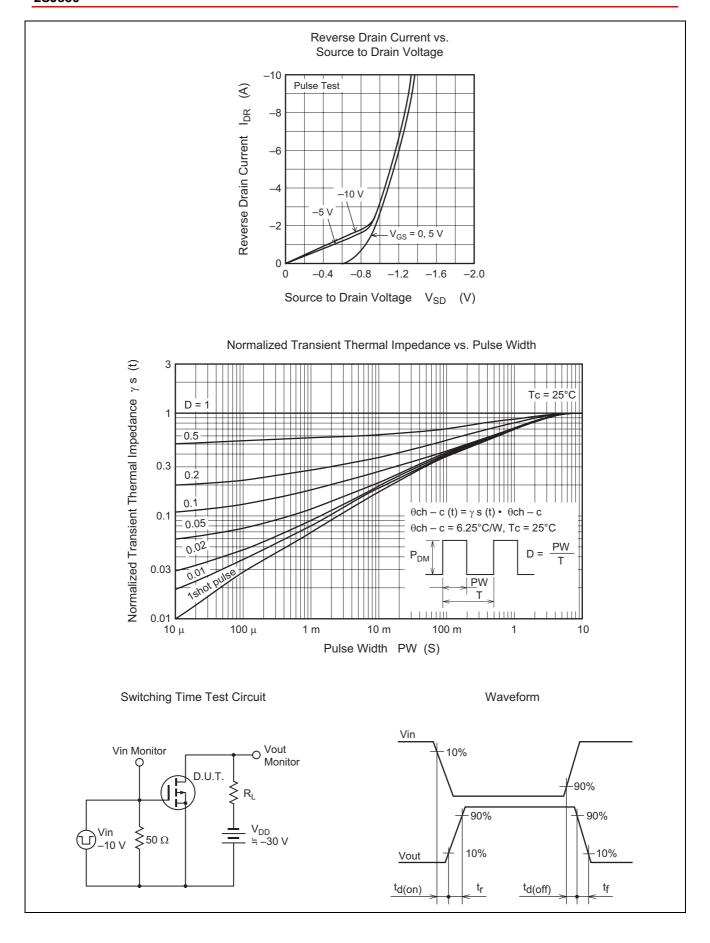
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V <sub>(BR) DSS</sub>	-120	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V <sub>(BR) GSS</sub>	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	-250	μΑ	$V_{DS} = -100 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V <sub>GS (off)</sub>	-1.0	_	-2.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R <sub>DS (on)</sub>	_	0.5	0.7	Ω	$I_D = -4 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note 3}}$
	R <sub>DS (on)</sub>	_	0.7	0.9	Ω	$I_D = -4 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y <sub>fs</sub>	3.0	5.0	_	S	$I_D = -4 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	_	900	_	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	_	265	_	рF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	65	_	pF	f = 1 MHz
Turn-on delay time	t <sub>d (on)</sub>	_	11	_	ns	$I_D = -4 A$
Rise time	t <sub>r</sub>	_	45	_	ns	V <sub>GS</sub> = -10 V
Turn-off delay time	t <sub>d (off)</sub>	_	170	_	ns	$R_L = 7.5 \Omega$
Fall time	t <sub>f</sub>	_	80	_	ns	
Body to drain diode forward voltage	$V_{DF}$	_	-1.2	_	V	$I_F = -6 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t <sub>rr</sub>	_	240	_	ns	$I_F = -6 \text{ A}, V_{GS} = 0$
						$di_F/dt = 50 A/\mu s$

Note: 3. Pulse test

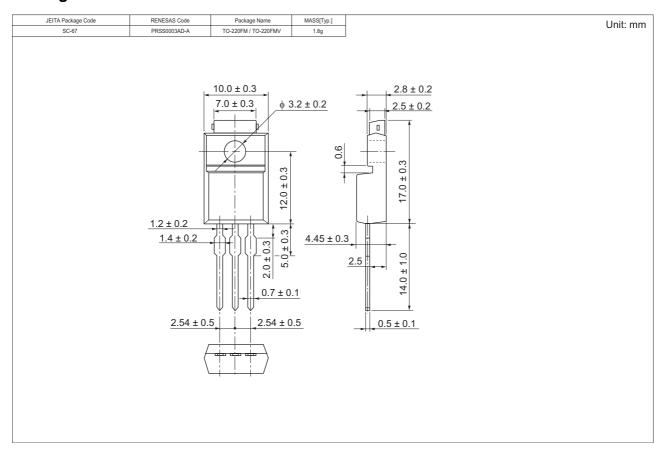
### **Main Characteristics**







## **Package Dimensions**



## **Ordering Information**

Part Name	Quantity	Shipping Container
2SJ350-E	500 pcs	Box (Sack)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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